

CMP polishing pads

PRODUCT DESCRIPTION

We offer a complete range of CMP polishing pads, covering both hard and soft pad types. These pads are engineered to support the full spectrum of CMP process steps, from oxide to metal layers, and are compatible with mainstream polishing platforms. This enables fabs to replace existing pad types with Dinglong's solutions without compromising performance or process stability.

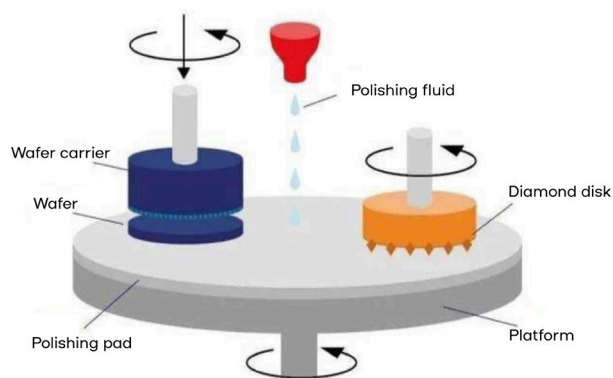
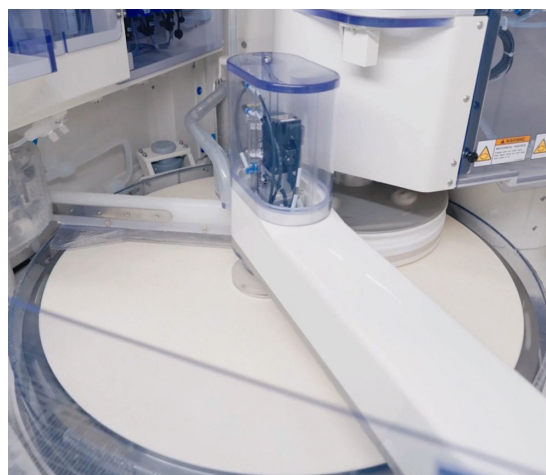
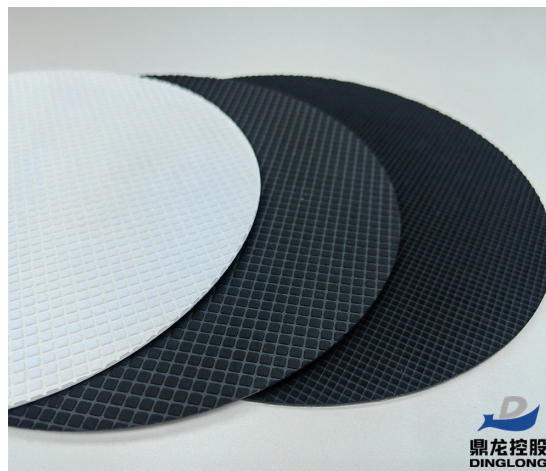
These CMP pads are designed with flexibility in mind. They can be customized to suit various wafer materials such as silicon, silicon carbide, and low-k dielectrics and tailored to specific process conditions. This ensures optimal material removal rates, surface planarity, and defect control across diverse applications.

FEATURES & ADVANTAGES

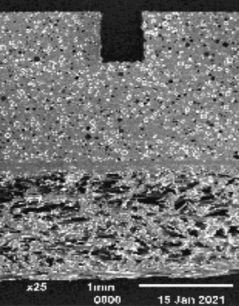
- Mature product with stable performance
- Custom options available
- Hard and soft polishing pads available

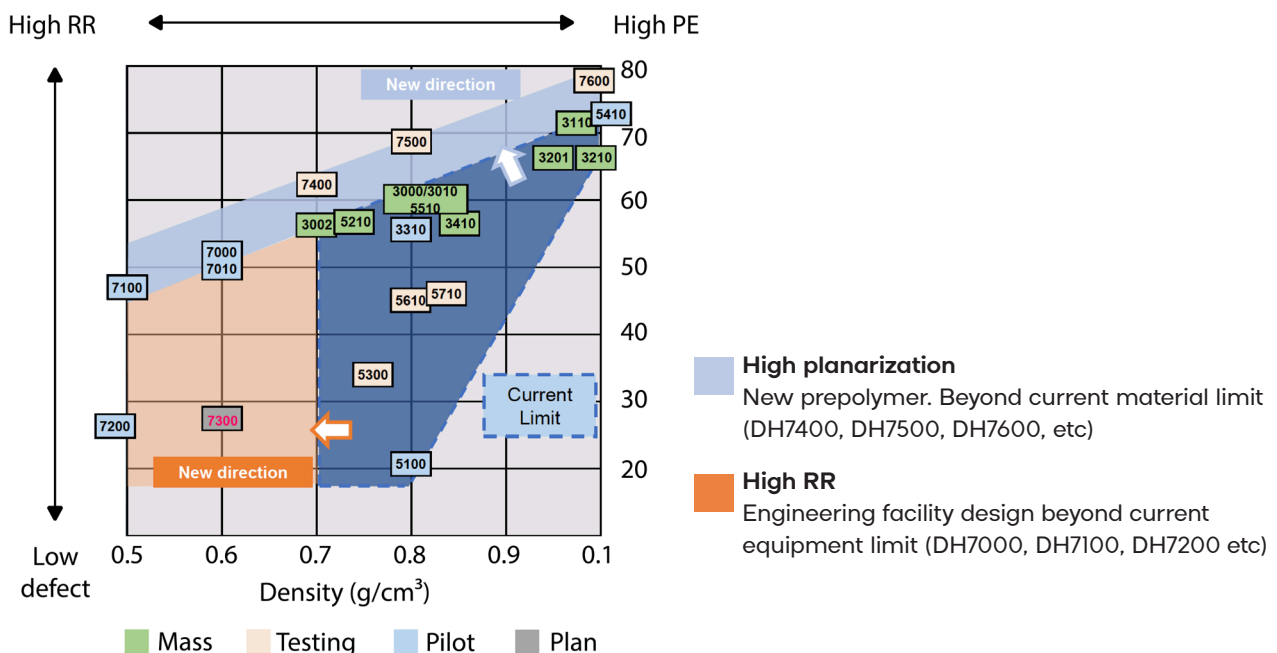
CUSTOM DESIGNED CMP PADS

Besides the mature CMP pads we also offer custom made CMP pads. We work closely together with our excellent CMP pad supplier, Hubei Dinglong, to ensure a product that perfectly meets customers needs.



DH SERIES CMP HARD PADS PRODUCTS

Structure	Product	Hardness (shore D)	Density (g/cm ³)	Applications
	DH3000	53.0-67.0	0.770-0.830	W/Cu/Poly/STI/ILD/Al 28nm+
	DH3002	52.0-62.0	0.670-0.730	W/Cu/Poly/STI/ILD 28nm+
	DH3110	66.0-76.0	0.940-1.070	Poly/ILD0/STI/Oxide 14nm+
	DH3200	55.0-75.0	0.950-1.050	SiC
	DH3201	61.0-73.0	0.920-0.980	Cu 28nm+
	DH3210	60.0-74.0	0.950-1.050	Cu 14nm+
	DH3310	53.5-63.5	0.770-0.830	Cu 28nm+
	DH3500	30.0-50.0	0.770-0.830	STI 28nm+
	DH3410	49.6-66.4	0.800-0.900	W/ILD 28nm+
	DH3410H	47.6-64.3	0.750-0.850	ILD0/STI 14nm+
	DH5010	55.0-75.0	0.770-0.830	MG W/Co 14nm+
	DH5100	5.0-30.0	0.700-0.900	Al 28nm+
	DH5410A	62.0-82.0	0.980-1.080	Cu/STI/ILD/Poly 14nm+
	DH5610	46.0-66.0	0.800-0.900	STI/Oxide 14nm+
	DH5210	55.5-61.5	0.650-0.750	STI/ILD0/Poly 14nm+
	DH5300	20.0-40.0	0.400-0.600	AL 28nm+
	DH5510	53.5-63.5	0.770-0.830	ILD 14nm+
	DH3600	60.0-70.0	0.830-0.930	ILD 45nm+
	DH7000 (Ultra-low density series)	41.0-61.0	0.450-0.650	Gridning/Bonding
	DH5610A (Low defect products)	38.0-58.0	0.770-0.830	Copper 14nm+



DR SERIES CMP SOFT PADS PRODUCTS

Structure	Product	Hardness (shore D)	Density (g/cm ³)	Applications
	DR9002	50.0-66.0	0.450-0.550	Cu/W/ILD/OX/Poly 28nm+
	DR9010	46.0-57.0	0.430-0.530	Cu/Poly/Co/W/STI 14nm+
	DR9018	50.0-66.0	0.490-0.690	Cu/Poly/Co/W/STI 14nm+
	DR9006	65.0-75.0	0.546-0.646	Wafer FP
	DR9020	56.0-72.0	0.530-0.670	Wafer FP
	DR9105	40.0-60.0	0.300-0.500	Wafer FP
	DR9100/9108	35.0-55.0	0.250-0.350	ILD/OX 28nm+
	DR9110	40.0-60.0	0.230-0.450	Cu/W 28nm+
	DR9620	67.0-77.0	0.270-0.350	Subpad
	DR9610	67.0-77.0	0.280-0.360	Subpad
	DR9616	30.0-70.0	0.200-0.400	Subpad
	DR9617	65.0-82.0	0.300-0.430	Wafer DSP
	DR9618	68.0-85.0	0.320-0.420	Wafer DSP
	DR9612	53.0-67.0	0.270-0.410	Grinding

